

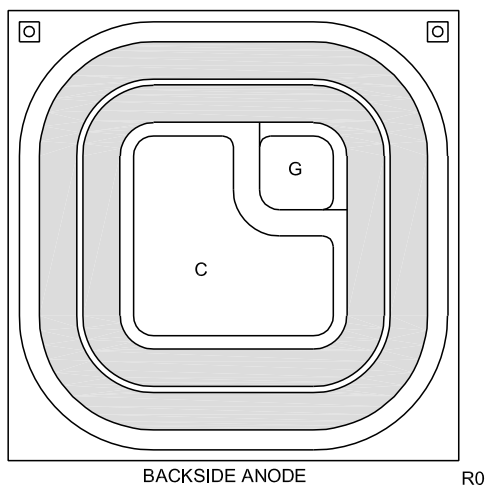
**PROCESS CPS041**  
**Silicon Controlled Rectifier**  
Sensitive Gate SCR Chip



**PROCESS DETAILS**

|                          |  |
|--------------------------|--|
| Process                  | GLASS PASSIVATED MESA                      |
| Die Size                 | 41 x 41 MILS                               |
| Die Thickness            | 8.7 MILS $\pm$ 0.6 MILS                    |
| Cathode Bonding Pad Area | 18 x 8 MILS                                |
| Gate Bonding Pad Area    | 7.1 x 7.1 MILS                             |
| Top Side Metalization    | Al - 45,000Å                               |
| Back Side Metalization   | Al/Mo/Ni/Ag - 20,000Å/5,000Å/5,000Å/2,000Å |

**GEOMETRY**



**GROSS DIE PER 4 INCH WAFER**  
6,474

**PRINCIPAL DEVICE TYPES**  
CS18D  
BRX49  
CS92D  
CS89M

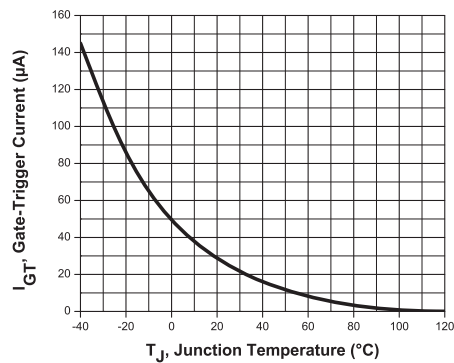
R3 (22-March 2010)

# PROCESS CPS041

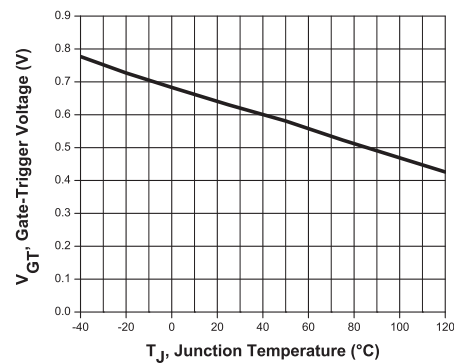
## Typical Electrical Characteristics



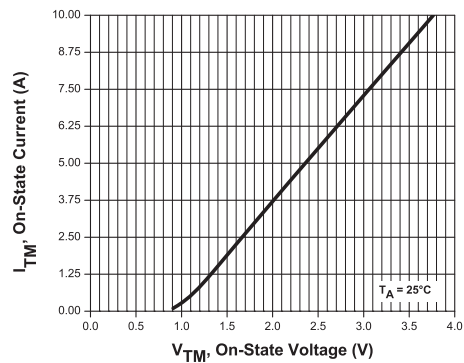
Typical Gate-Trigger Current



Typical Gate-Trigger Voltage



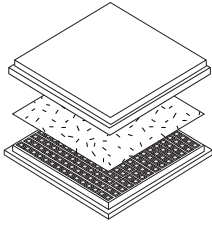
Typical On-State Voltage



R3 (22-March 2010)

## BARE DIE PACKING OPTIONS

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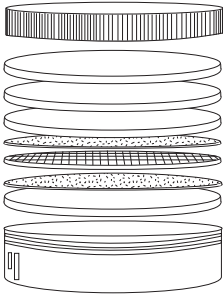


### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

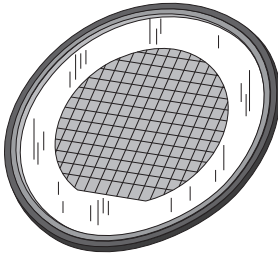
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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

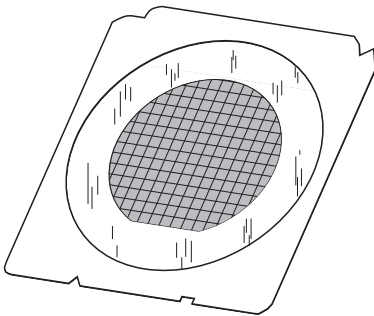
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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

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### SAWN WAFER ON METAL FRAME

**WS:** Full wafer, sawn and mounted on metal frame,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WS)

R0 (7-December 2015)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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**Worldwide Field Representatives:**  
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**Worldwide Distributors:**  
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For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: [www.centalsemi.com/terms](http://www.centalsemi.com/terms)



<http://www.centrasemi.com>

PDN01059

1/13/17

N/A

N/A

Please be advised that Central Semiconductor must immediately discontinue the product(s) listed in the attached PDN notice. We are unable to accept any further orders for these products unless we have available inventory on hand.

You may have purchased one or more of the products listed. Please do not hesitate to contact your local Central Semiconductor sales representative with any questions or needs you may have. Central regrets any inconvenience this may cause.

Sincerely,

Central Semiconductor Corp.



<http://www.centrasemi.com>

PDN01059

1/13/17

N/A

N/A

Summary: The CPS041 wafer process has been discontinued; the devices below are now classified as End of Life (EOL).

Although Central Semiconductor Corp. makes every effort to continue to produce devices that have been proclaimed EOL (End of Life) by various manufacturers, it is an accepted industry practice to discontinue certain devices when customer demand falls below a minimum level of sustainability. Accordingly, the following product(s) have been transitioned to End of Life status as part of Central's Product Management Process. Any replacement product will be noted below. The effective date for placing the last purchase order will be six(6) months from the date of this notice and twelve(12) months from the notice date for final shipments; this may be extended if inventory is available.

| <u>Central Part Number</u> | <u>Replacement</u> |
|----------------------------|--------------------|
| CPS041-CS18B-WN            | CPS053-CS18B-WN    |
| CPS041-2N5060-CT           | CPS053-2N5060-CT   |
| CPS041-2N5064-CT           | CPS053-2N5064-CT   |
| CPS041-2N5064-WN           | CPS053-2N5064-WN   |
| CPS041-2N878-CT            | CPS053-2N878-CT    |
| CPS041-2N878-WN            | CPS053-2N878-WN    |

Central would be happy to assist you by providing additional information or technical data to help locate an alternate source if we have no replacement available. Please email your requests to [engineering@centrasemi.com](mailto:engineering@centrasemi.com).